

Tekdense Unveils Magpie II: A New Benchmark in Compact Rugged Computing

Tekdense proudly unveils Magpie II, the next evolution of its rugged embedded computing platform, engineered to take compact mission-critical computing to a new level. Building on the proven foundation of the Magpie platform, Magpie II brings together enhanced processing capabilities, flexible I/O, low-power operation, and ruggedized design in an exceptionally compact Small Form Factor (SFF) architecture.



At the heart of the Magpie II evolution are two distinct computing variants, engineered to deliver the right balance of performance and efficiency for demanding mission requirements. Magpie II-T features the 11th Gen Intel® Core™ i7-1185GRE processor with 4C at 2.8 GHz, while Magpie II-R advances the platform with the 13th Gen Intel® Core™ i7-1365URE, featuring 2P/8E at 1.70 GHz ,15W. Both variants support up to 1980GB M.2 SATA/NVMe storage, Intel® Iris® Xe Graphics, DisplayPort, and a versatile I/O architecture, bringing high-performance computing, connectivity, and application flexibility together in a compact rugged platform.

Built on an open COM Express (COMe) architecture, Magpie II combines enhanced processing, flexible I/O, and exceptional SWaP efficiency in a 5.12 (W) × 2.36 (H) × 5.17(L) inches, ≤2.9 lbs rugged platform. “Magpie II represents a significant advancement in rugged embedded computing, giving engineers the performance and flexibility to meet evolving defense and aerospace demands,” said Mr. Pawan Seth, Director at Tekdense . With conduction cooling, 28VDC input, and <50W power consumption, Magpie II delivers mission-ready performance without compromise.

Magpie II is now available for orders and integration in both Magpie II-T and Magpie II-R configurations. Customers can explore tailored configurations to address specific defense, aerospace, and embedded application requirements.

For more details, visit [fanless-micro-embedded-computer-magpieII](https://www.tekdense.com/fanless-micro-embedded-computer-magpieII) or email sales@tekdense.com.

About Tekdense

Tekdense is a U.S.-based provider of high-performance computing systems and custom embedded solutions for industrial, aerospace, and defense applications. Headquartered in Miami, Florida, Tekdense specializes in Small Form Factor (SFF) platforms, COTS computers, custom design and built-to-print solutions engineered for harsh and mission-critical environments.

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